/ Descriptions

SOT-23 PNP Silicon PNP transistor in a SOT-23 Plastic Package.

/ Features

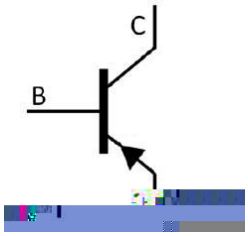
BCW32

Low current, low voltage, complements to BCW32.

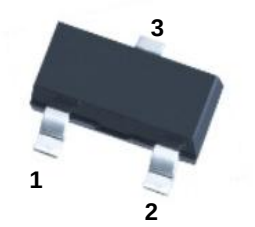
/ Applications

General purpose switching and amplifier applications.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Emitter PIN 3 Collector

/ h_{FE} Classifications & Marking

h_{FE} Range	215~500
Marking	HC2

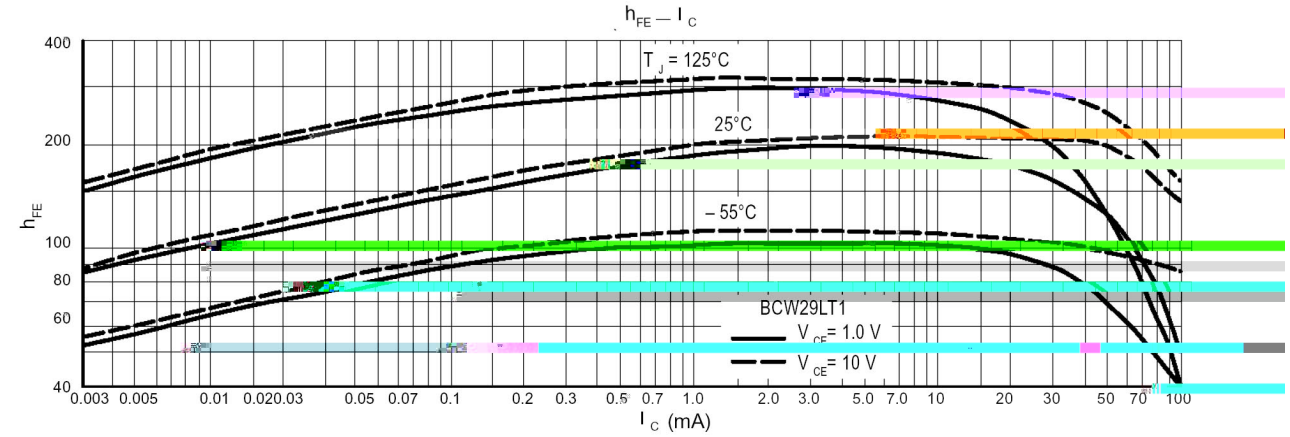
/ Absolute Maximum Ratings(Ta=25)

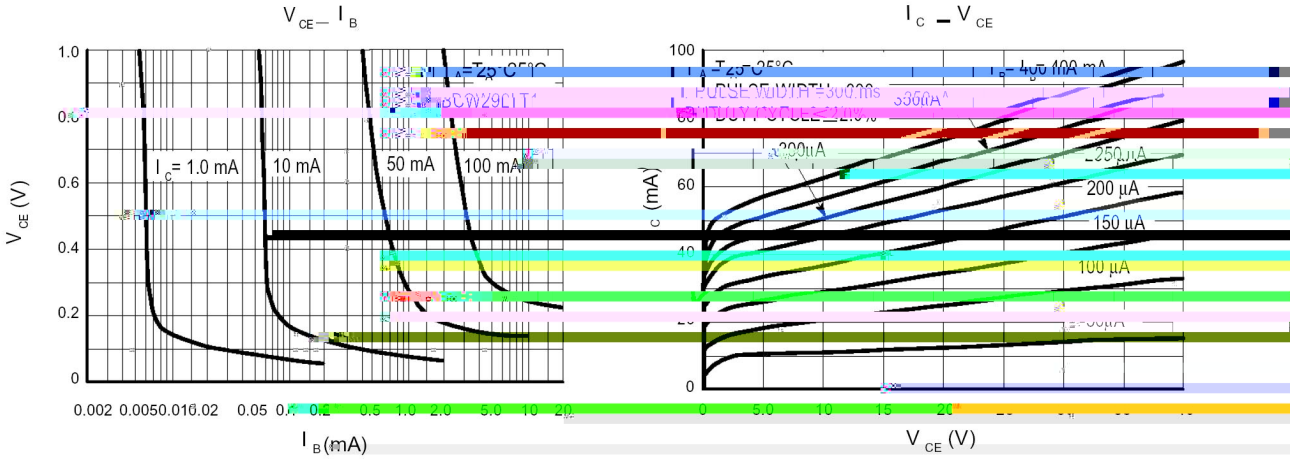
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-32	V
Collector to Emitter Voltage	V_{CEO}	-32	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current(DC)	I_C	-100	mA
Peak Collector Current	I_{CM}	-200	mA
Peak Base Current	I_{BM}	-200	mA
Collector Power Dissipation	P_C	250	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

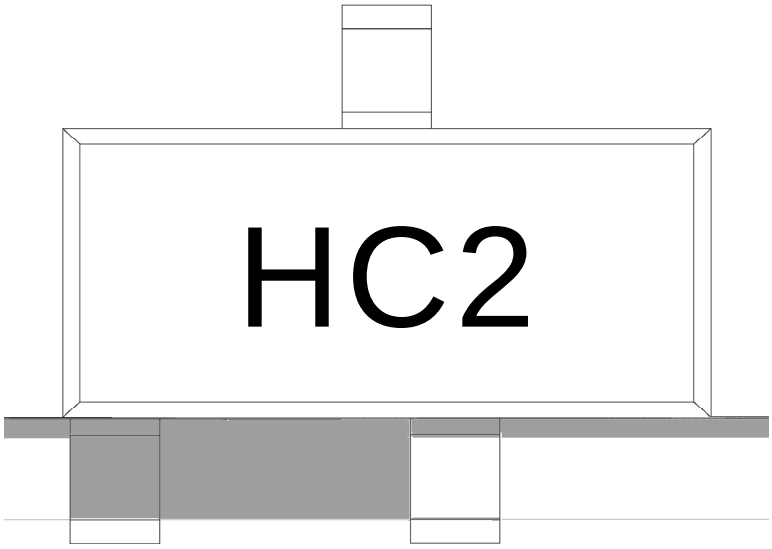
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	V_{CB}=-32 V I_E=0			-0.1	μA
Emitter Base Cut-Off Current	I_{EBO}	V_{EB}=-5.0V I_C=0			-0.1	μA
DC Current Gain	$h_{FE(1)}$	V_{CE}=-5.0V I_C=-2.0mA	215		500	
	$h_{FE(2)}$	V_{CE}=-5.0V I_C=-10μA		150		
Collector to Emitter Saturation Voltage	$V_{CE(sat)(1)}$	I_C=-10mA I_B=-0.5mA		-80	-300	mV
	$V_{CE(sat)(2)}$	I_C=-50mA I_B=-2.5mA		-150		mV
Base to Emitter Saturation Voltage	$V_{BE(sat)(1)}$	I_C=-10mA I_B=-0.5mA		-720		mV
	$V_{BE(sat)(2)}$	I_C=-50mA I_B=-2.5mA		-810		mV
Base-Emitter On Voltage	V_{BE}	V_{CE}=-5.0V I_C=-2.0mA	-600		-750	mV
Transition Frequency	f_T	I_C=-10mA V_{CE}=-5.0V f=100MHz	100			MHz
Collector Capacitance	C_C	V_{CB}=-10V I_E=0 f=1MHz		4.5		pF
Noise Figure	NF	V_{CE}=-5.0V I_C=-200μA R_S=2KΩ f=1KHz B=200Hz			10	dB

/ Electrical Characteristic Curve





/ Marking Instructions



H

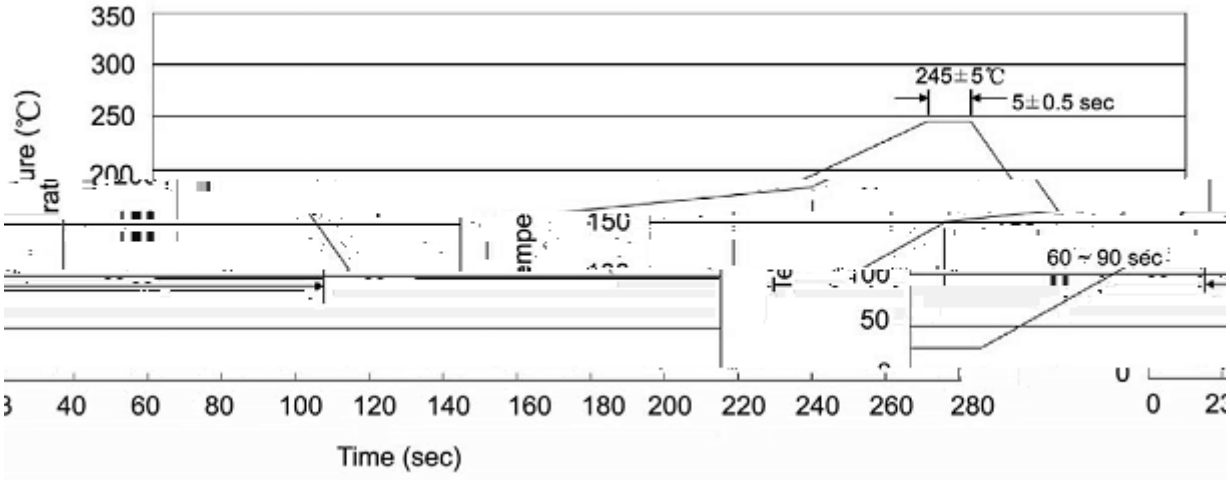
C2

Note:

H: Company Code.

C2: Product Type Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1 25 150 60 90sec;

1.Preheating:25~150 , Time:60~90sec.

2 245±5 5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3 2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱
						ρ		

/ Notices